IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information						
Supplie	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
onsemi												2025-06-07			
Contact Name			Title - Contact				Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*		Title - Representative				Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Dat	Date Version Manufacturing Site		ring Site	V	Veight*	UOM	Unit Type	
		FFSP0865A		SiC TO220 SBD 8A 650V		2025-06-07			CPA		1	978.421	mg	Each	
Manufa	ecturing Process Information	tion										,			
	Terminal Plating / Grid Array Material T		Cerminal Base Alloy J-STD-02		-STD-020 MSI	L Rating	Peak Process Body Temperat		ture Max Time at Peak Tempe		Temperatu	ire Numbe	er of Reflow Cyc	eles	
	Matte Tin (Sn) - annealed		CU Alloy NA		NA.		0 C		30	30 seco		ls 3			
Comments	S														
				<u> </u>		·					·				
or more	information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Isability and the Company's remedies for issues that arise regarding information the Supplier pro										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.81	mg	Supplier	Silicon Carbide	409-21-2		2.81	mg
Die Attach Solder	1.111	mg	Supplier	Silver (Ag)	7440-22-4		0.0278	mg
			A	Lead (Pb)	7439-92-1	7a	1.0277	mg
			Supplier	Tin (Sn)	7440-31-5		0.0555	mg
Lead Frame	1444.76	mg	В	Nickel (Ni)	7440-02-0		1.0113	mg
			Supplier	Iron (Fe)	7439-89-6		1.4448	mg
			Supplier	Copper (Cu)	7440-50-8		1441.8705	mg
			Supplier	Phosphorus (P)	7723-14-0		0.4334	mg
Mold Compound-Black	518.4	mg		Proprietary	proprietary data		25.92	mg
			Supplier	Carbon Black (C)	1333-86-4		2.592	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		386.208	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		77.76	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		25.92	mg
Plating	8.9	mg	Supplier	Tin (Sn)	7440-31-5		8.9	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg